

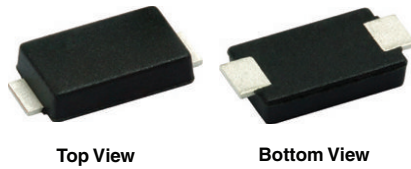


# THE DATASHEET OF VSSAF515HM3/H



# Surface-Mount TMBS<sup>®</sup> (Trench MOS Barrier Schottky) Rectifier

## eSMP<sup>®</sup> Series



Top View Bottom View

### SlimSMA (DO-221AC)

Cathode Anode

## FEATURES

- Very low profile - typical height of 0.95 mm
- Ideal for automated placement
- Trench MOS Schottky technology
- Low power losses, high efficiency
- Low forward voltage drop
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- AEC-Q101 qualified available  
- Automotive ordering code: base P/NHM3
- Material categorization: for definitions of compliance please see [www.vishay.com/doc?99912](http://www.vishay.com/doc?99912)

AUTOMOTIVE  
GRADE  
Available



RoHS  
COMPLIANT  
HALOGEN  
FREE

## LINKS TO ADDITIONAL RESOURCES



3D Models

### PRIMARY CHARACTERISTICS

$I_{F(AV)}$	5.0 A
$V_{RRM}$	150 V
$I_{FSM}$	100 A
$V_F$ at $I_F = 5.0$ A (125 °C)	0.66 V
$T_J$ max.	150 °C
Package	SlimSMA (DO-221AC)
Circuit configuration	Single

## TYPICAL APPLICATIONS

For use in high frequency inverters, freewheeling, DC/DC converters, and polarity protection in commercial, industrial, and automotive applications.

## MECHANICAL DATA

**Case:** SlimSMA (DO-221AC)

Molding compound meets UL 94 V-0 flammability rating

Base P/N-M3 - halogen-free, RoHS-compliant

Base P/NHM3 - halogen-free, RoHS-compliant, and AEC-Q101 qualified

**Terminals:** matte tin plated leads, solderable per J-STD-002 and JESD 22-B102

M3 and HM3 suffix meets JESD 201 class 2 whisker test

**Polarity:** color band denotes cathode end

### MAXIMUM RATINGS ( $T_A = 25$ °C unless otherwise noted)

PARAMETER	SYMBOL	VSSAF515	UNIT
Device marking code		V515	
Maximum repetitive peak reverse voltage	$V_{RRM}$	150	V
Maximum average forward rectified current	$I_{F(AV)}^{(1)}$	1.8	A
	$I_{F(AV)}^{(2)}$	5.0	
Peak forward surge current 10 ms single half sine-wave superimposed on rated load	$I_{FSM}$	100	A
Operating junction and storage temperature range	$T_J, T_{STG}$	-40 to +150	°C

#### Notes

(1) Free air, mounted on recommended copper pad area

(2) Mounted on 30 mm x 30 mm pad area



ELECTRICAL CHARACTERISTICS ( $T_A = 25\text{ }^\circ\text{C}$ unless otherwise noted)						
PARAMETER	TEST CONDITIONS		SYMBOL	TYP.	MAX.	UNIT
Instantaneous forward voltage	$I_F = 2.5\text{ A}$	$T_A = 25\text{ }^\circ\text{C}$	$V_F^{(1)}$	0.77	-	V
	$I_F = 5.0\text{ A}$			1.02	1.10	
	$I_F = 2.5\text{ A}$	$T_A = 125\text{ }^\circ\text{C}$		0.58	-	
	$I_F = 5.0\text{ A}$			0.66	0.75	
Reverse current	$V_R = 100\text{ V}$	$T_A = 25\text{ }^\circ\text{C}$	$I_R^{(2)}$	0.01	-	mA
		$T_A = 125\text{ }^\circ\text{C}$		0.6	-	
	$V_R = 150\text{ V}$	$T_A = 25\text{ }^\circ\text{C}$		-	0.2	
		$T_A = 125\text{ }^\circ\text{C}$		2	5	
Typical junction capacitance	4.0 V, 1 MHz		$C_J$	280	-	pF

**Notes**

- (1) Pulse test: 300  $\mu\text{s}$  pulse width, 1 % duty cycle  
(2) Pulse test: Pulse width  $\leq 40\text{ ms}$

THERMAL CHARACTERISTICS ( $T_A = 25\text{ }^\circ\text{C}$ unless otherwise specified)			
PARAMETER	SYMBOL	VSSAF515	UNIT
Typical thermal resistance	$R_{\theta JA}^{(1)(2)}$	115	$^\circ\text{C/W}$
	$R_{\theta JM}^{(3)}$	12	

**Notes**

- (1) Free air, mounted on recommended PCB, 2 oz. pad area; thermal resistance  $R_{\theta JA}$  - junction to ambient,  $R_{\theta JM}$  - junction to mount  
(2) The heat generated must be less than thermal conductivity from junction-to-ambient:  $dP_D/DT_J < 1/R_{\theta JA}$   
(3) Mounted on 30 mm x 30 mm pad area

ORDERING INFORMATION (Example)				
PREFERRED P/N	UNIT WEIGHT (g)	PREFERRED PACKAGE CODE	BASE QUANTITY	DELIVERY MODE
VSSAF515-M3/H	0.032	H	3500	7" diameter plastic tape and reel
VSSAF515-M3/I	0.032	I	14 000	13" diameter plastic tape and reel
VSSAF515HM3/H <sup>(1)</sup>	0.032	H	3500	7" diameter plastic tape and reel
VSSAF515HM3/I <sup>(1)</sup>	0.032	I	14 000	13" diameter plastic tape and reel

**Note**

- (1) AEC-Q101 qualified

**RATINGS AND CHARACTERISTICS CURVES** ( $T_A = 25\text{ }^\circ\text{C}$  unless otherwise noted)

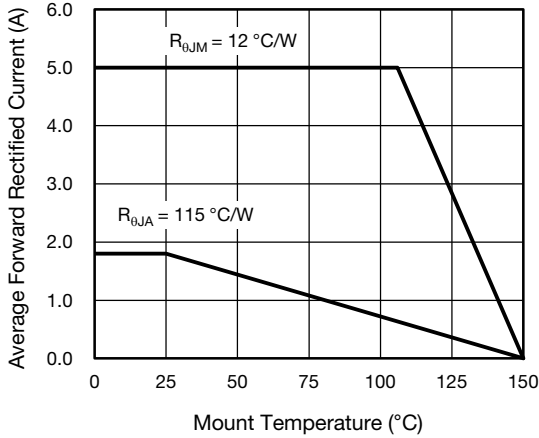


Fig. 1 - Maximum Forward Current Derating Curve

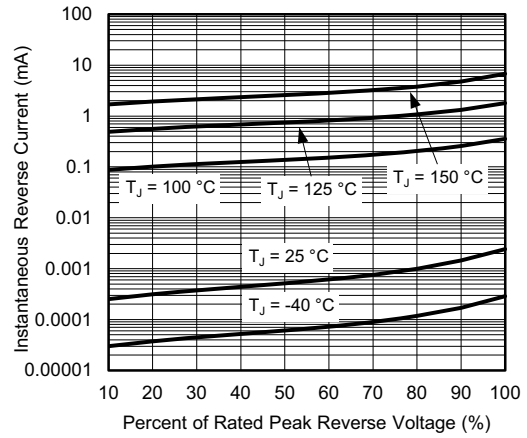


Fig. 4 - Typical Reverse Leakage Characteristics

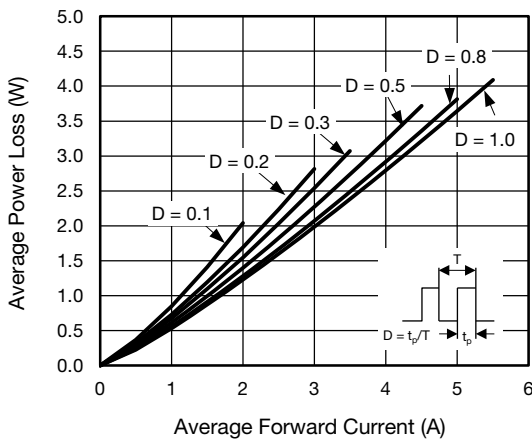


Fig. 2 - Forward Power Loss Characteristics

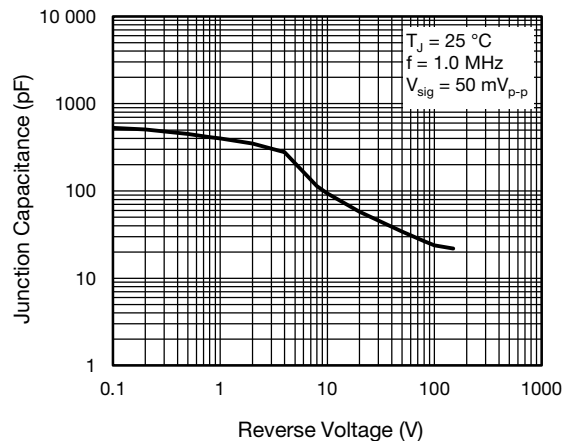


Fig. 5 - Typical Junction Capacitance

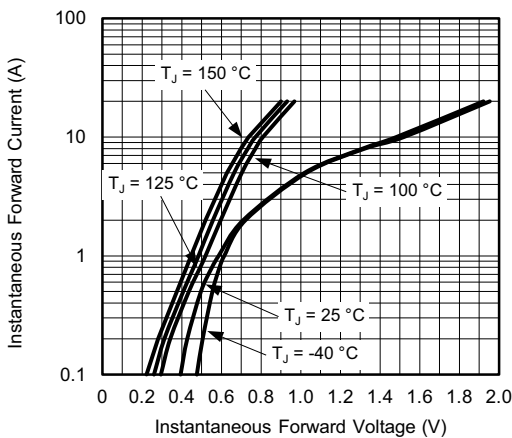


Fig. 3 - Typical Instantaneous Forward Characteristics

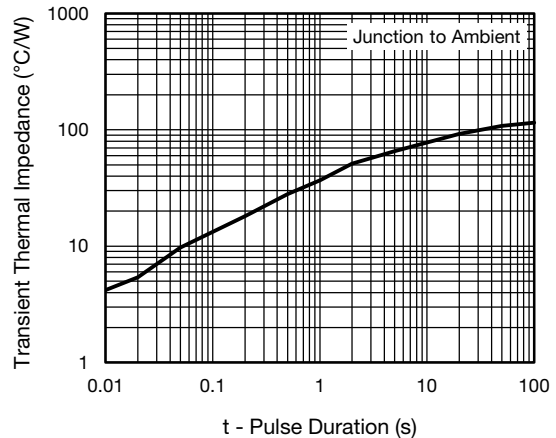


Fig. 6 - Typical Transient Thermal Impedance

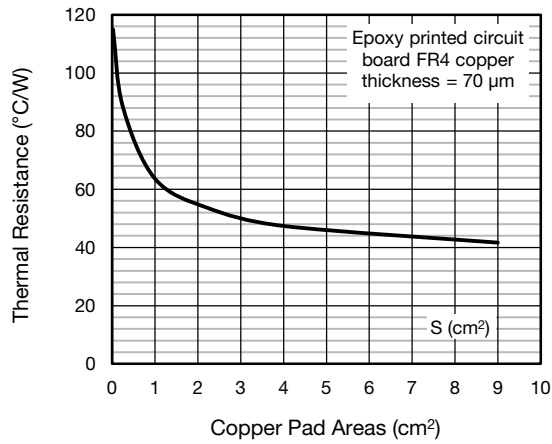
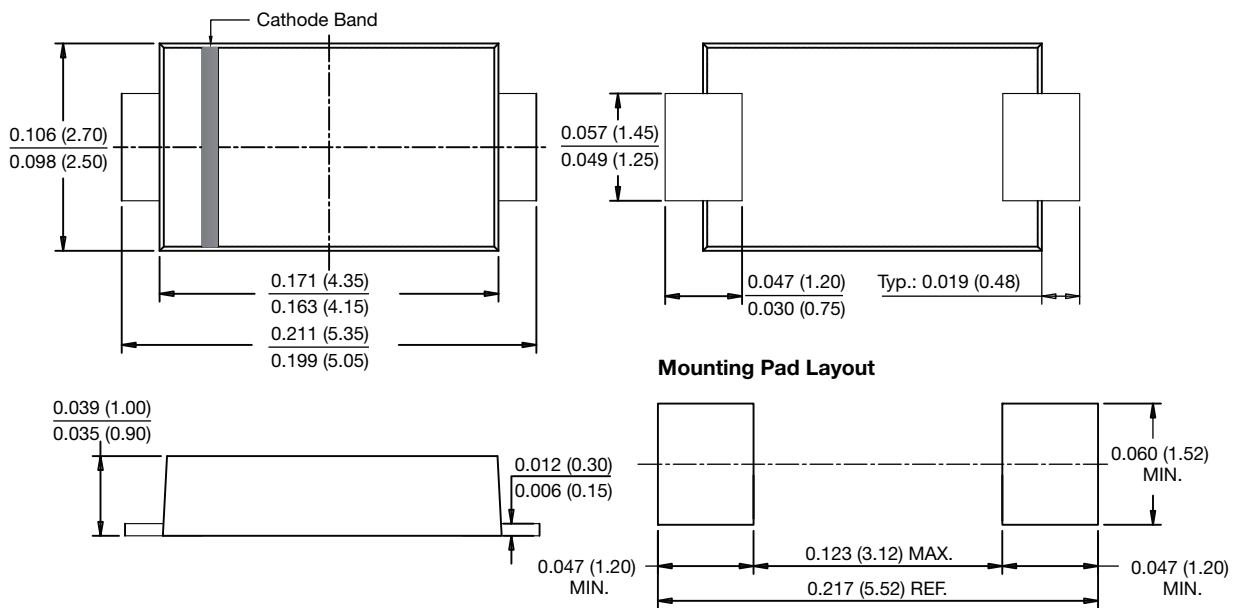


Fig. 7 - Thermal Resistance Junction to Ambient vs. Copper Pad Area

**PACKAGE OUTLINE DIMENSIONS** in inches (millimeters)

**SlimSMA (DO-221AC)**





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